

Title (en)

METHOD FOR DETERMINING AT LEAST ONE PARAMETER FOR CUTTING A BLOCK OF SEMICONDUCTOR MATERIAL AND DEVICE IMPLEMENTING THE METHOD

Title (de)

VERFAHREN ZUR BESTIMMUNG MINDESTENS EINES PARAMETERS ZUM SCHNEIDEN EINES BLOCKS AUS HALBLEITERMATERIAL UND VORRICHTUNG ZUR DURCHFÜHRUNG DES VERFAHRENS

Title (fr)

PROCEDE DE DETERMINATION D'AU MOINS UN PARAMETRE DE COUPE D'UNE BRIQUE D'UN MATERIAU SEMI-CONDUCTEUR ET DISPOSITIF METTANT EN OEUVRE LE PROCEDE

Publication

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Application

**EP 20797779 A 20201103**

Priority

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Abstract (en)

[origin: WO2021089507A1] One aspect of the invention relates to a method (100) for determining at least of parameter for cutting C a block of semiconductor material, comprising: - a step (1E1) of determining the density and/or the size of the precipitates present in the block; - on the basis of at least one determining threshold, a step (1E2) of dividing the block into a plurality of zones, each zone being associated with a class chosen from at least two classes; - depending on the proportion of zones that are associated with each class, a step (1E3) of determining at least one cutting parameter.

IPC 8 full level

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Citation (search report)

See references of WO 2021089507A1

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